

parent case

Form PTO-1449

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.  
MI22-2393PRIORITY SERIAL NO.  
09/592,604LIST OF ART CITED BY APPLICANT  
(Use several sheets if necessary)APPLICANT  
Fernando GonzalezPRIORITY FILING DATE  
June 12, 2000PRIORITY GROUP  
2818

## U.S. PATENT DOCUMENTS

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
TL	AA	5,298,449	03/94	Kikuchi			
	AB	5,374,564	12/94	Bruehl			
	AC	5,855,693	01/99	Murari et al.			
	AD	5,877,070	03/99	Goesle et al.			
	AE	5,882,987	03/99	Srikrishnan			
	AF	5,894,152	04/99	Jaso et al.			
	AG	5,953,622	09/99	Lee et al.			
	AH	6,004,406	12/99	Kobayashi et al.			
	AI	6,309,945 B1	10/01	Sato et al.			
	AJ	6,429,070 B1	08/02	Gonzalez et al.			
	AK	6,384,439 B1	05/02	Walker			
		6,423,992 B2	07/02	Fukuda, et al.			
	AL	5,998,847	12/99	Assaderaghi, et al.			

## FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
	AM							
	AN							
	AO							
	AP							
	AQ							

## OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

TL	AR	Göscle, U. et al., "Semiconductor Wafer Bonding: Science, Technology, and Applications", Electrochemical Society Proceedings
		Vol. 97-36, (©1998), pp. 400-425, 436-445.
	AS	

EXAMINER

DATE CONSIDERED

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

EV318283495